MICROFLUIDICS

Microfluidics/Microfabrication Facility, Harvard Medical School

PROCEDURE FOR SOLVENT CLEANING OF SILICON WAFERS

1. Put the wafer on top of the spin coater chuck located in the fume hood-wet bench.

2. Check recipe conditions for:

a. Spin speed range between 2000 and 3000rpm

b. Total time of 8 mins

3. For 1 min, pour Acetone from the squeezable bottle on the rotating wafer and use foam-cotton swab to remove gently any residues. Do not stop pouring acetone during this lapse of time.

4. For 1 min, pour Methanol from the squeezable bottle on the rotating wafer and use foam-cotton swab to remove gently any residues. Do not stop pouring acetone during this lapse of time.

5. For 1 min, pour Isopropyl Alcohol from the squeezable bottle on the rotating wafer and use foam-cotton swab to remove gently any residues. Do not stop pouring acetone during this lapse of time.

6. Rinse wafer with DI water during 1 min.

7. Use pressurized nitrogen to blow dry for 1 min.

8. Turn off the spinner vacuum and proceed to remove the wafer from the chuck using tweezers to avoid touching the clean surface.